



Features:

- Isolated mounting base 3000V~
 - Pressure contact technology with Increased power cycling capability
 - Space and weight saving
- Typical Applications**
- AC/DC Motor drives
 - Various rectifiers
 - DC supply for PWM inverter

V _{RSM}	V _{RRM}	Type & Outline
900V	800V	MDx160-08-216F3
1100V	1000V	MDx160-10-216F3
1300V	1200V	MDx160-12-216F3
1500V	1400V	MDx160-14-216F3
1700V	1600V	MDx160-16-216F3
1900V	1800V	MDx160-18-216F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _J (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			160	A
I _{F(RMS)}	RMS forward current		150			251	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			12	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			4.60	KA
I ² t	I ² T for fusing coordination	V _R =0.6V _{RRM}				106	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.80	V
r _F	Forward slop resistance					1.35	mΩ
V _{FM}	Peak forward voltage	I _{FM} =480A	25			1.56	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.230	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.08	°C /W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I _{iso} :1mA(max)	3000				V
F _m	Terminal connection torque(M6)				6		N·m
	Mounting torque(M6)				6		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				285		g
Outline				216F3			

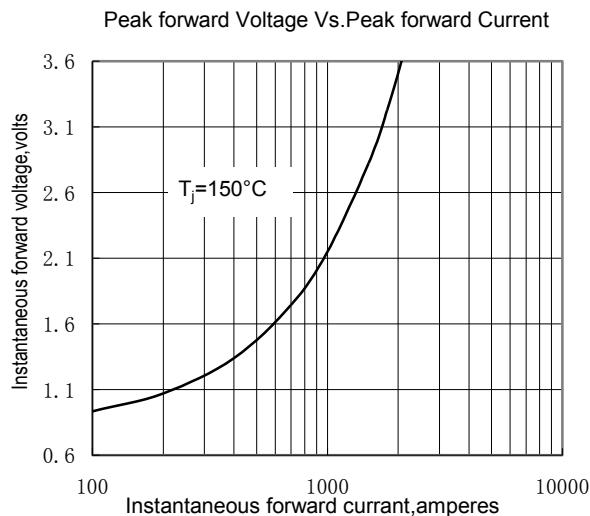


Fig.1

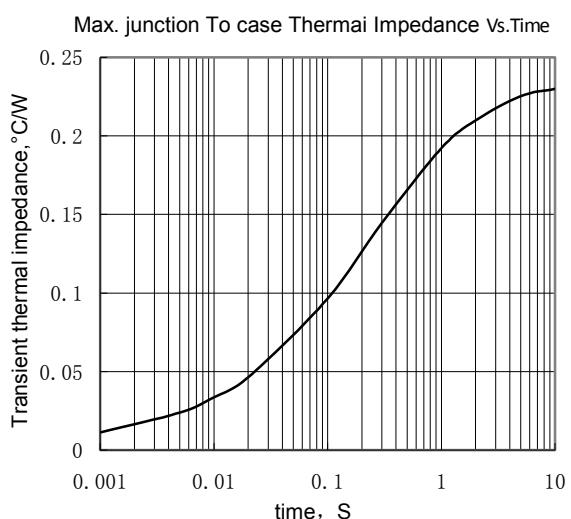


Fig.2

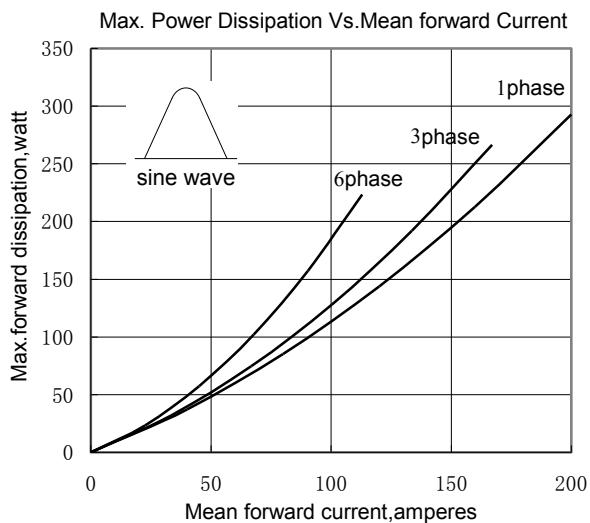


Fig.3

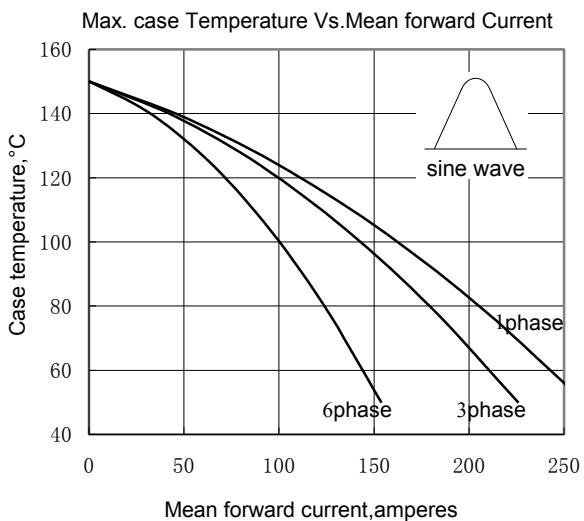


Fig.4

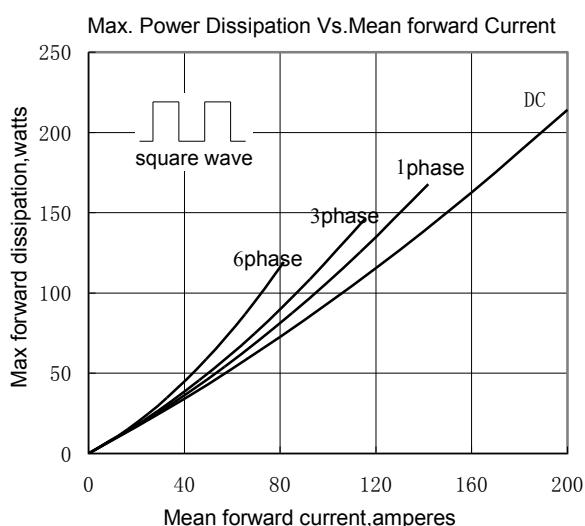


Fig.5

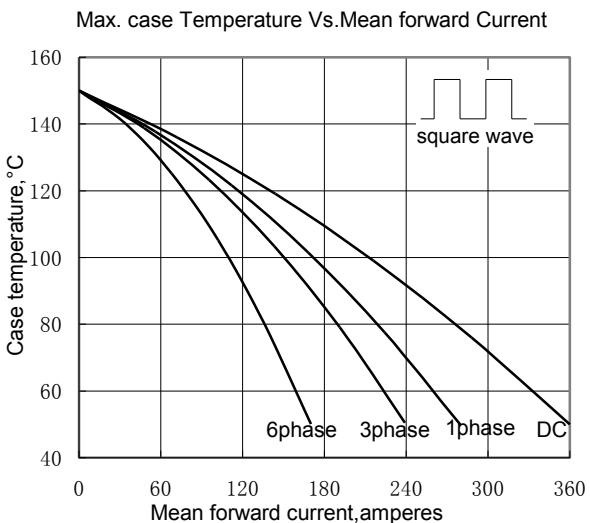


Fig.6

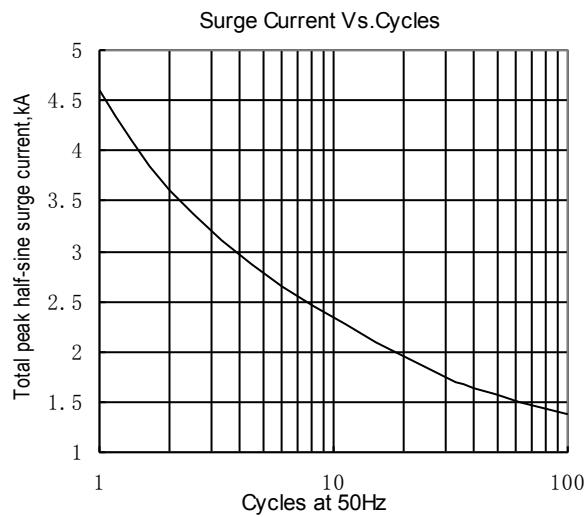


Fig.7

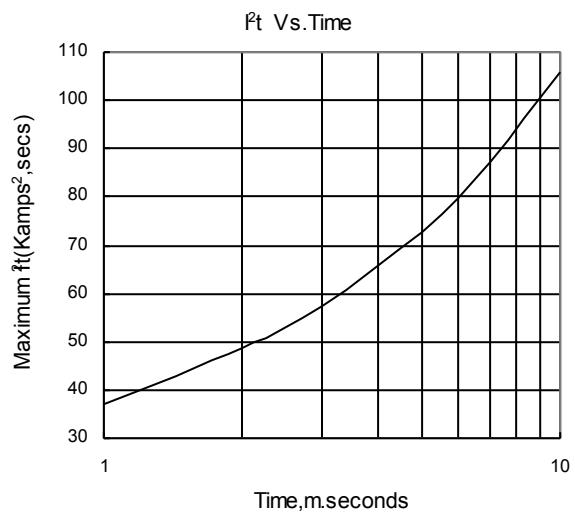
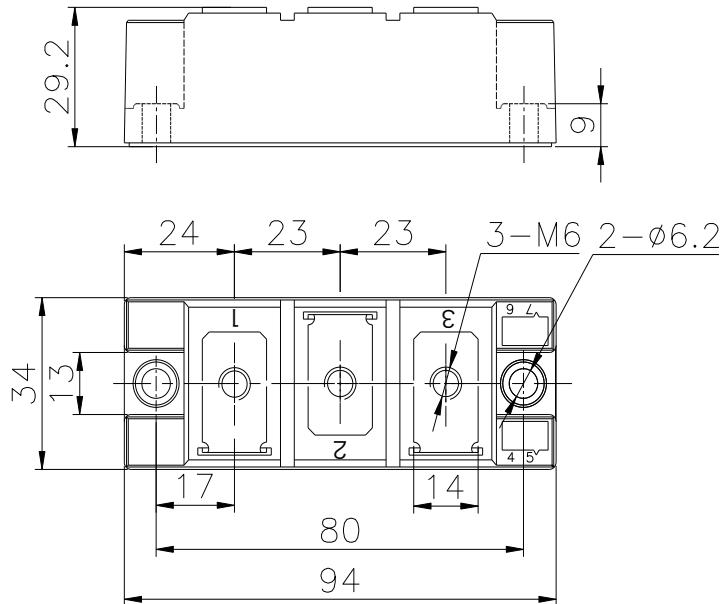


Fig.8

Outline:



216F3

